

PRODUCTION DATA SHEET

ABSOLUTE MAXIMUM RATINGS

Supply Input Voltage (V _{IN})	0.3V to 7V
All Input Pins	0.3V to $V_{\rm IN}$
SRC Input Current	
Operating Temperature Range	40°C to 85°C
Maximum Operating Junction Temperature	150°C
Storage Temperature Range	65°C to 150°C
Lead Temperature (Soldering 10 seconds)	235°C
Peak Package Solder Reflow Temp (40 seconds max. exposure)	260°C (+0, -5)

Note: Exceeding these ratings could cause damage to the device. All voltages are with respect to Ground. Currents are positive into, negative out of specified terminal.

THERMAL DATA

DU Plastic MSOP 10-Pin

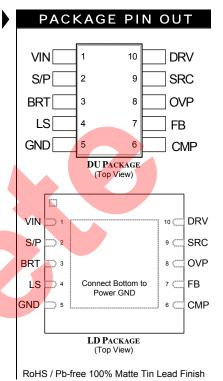
THERMAL RESISTANCE-JUNCTION TO AMBIENT, θ_{JA} 113°C/W

Plastic MLP 10-Pin

THERMAL RESISTANCE-JUNCTION TO AMBIENT, θ_{JA} 49°C/W

Junction Temperature Calculation: $T_J = T_A + (P_D \times \theta_{JA})$.

The θ_{JA} numbers are guidelines for the thermal performance of the device/pc-board system. All of the above assume no ambient airflow.



FUNCTIONAL PIN DESCRIPTION				
Name	Description			
V _{IN}	Unregulated IC Supply Voltage Input – Input range from 2.0V to 5.5V. Bypass with a 1μF or greater capacitor for operation at low voltage.			
GND	Common terminal for ground reference.			
BRT	LED Current Adjustment - Accepts a DC analog input.			
FB	LED Current Sense – Connect to current sense resistor.			
SRC	MOSFET Current Sense Input - Connects to the external N-Channel MOSFET source.			
DRV	MOSFET Gate Driver – Connects to an external N-Channel MOSFET gate.			
OVP	Over Voltage Programming Pin – Connects to a resistor divider between the output load and GND to set the maximum output voltage.			
LS	Light Sensor Input – Allows light sensor current input to be modulated by the PWM control causing LED brightness to be a product of the PWM duty cycle and ambient light level. If unused, leave LS pin open.			
CMP	Compensation Pin – Apply a 0.1µF capacitor for loop compensation.			
S/P	Shutdown/PWM Pin – A logic low longer than 100µs causes the IC to enter Shutdown mode. Applying a PWM signal to this pin and a filter capacitor to the BRT pin allows amplitude independent PWM control.			

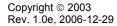


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ELECTRICAL CHARACTERISTICS

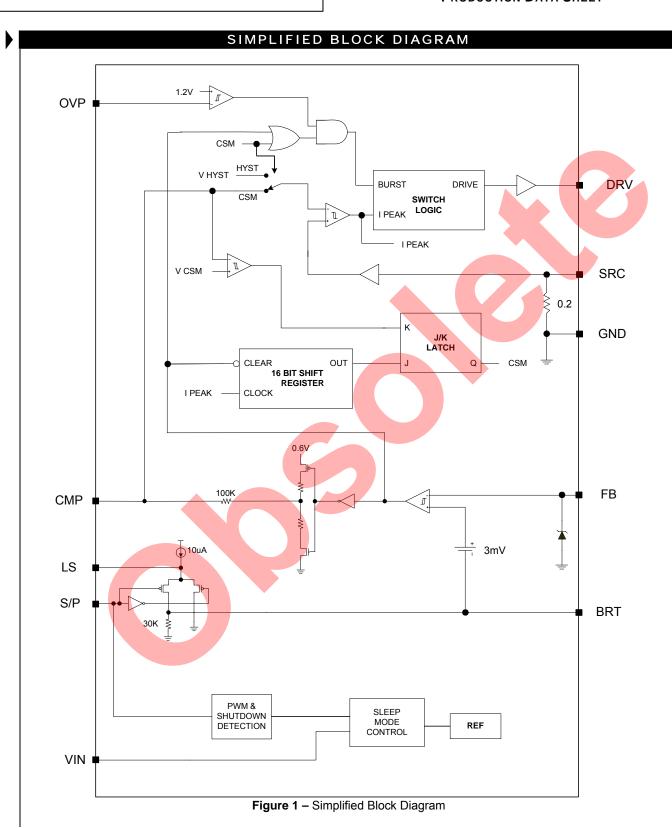
Unless otherwise specified, the following specifications apply over the operating ambient temperature -40°C $\leq T_A \leq 85$ °C except where otherwise noted and the following test conditions: V_{IN} = 3.6V, I_{LOAD} = 20mA

Parameter	Symbol	mbol Test Conditions	LX1994			Units
Parameter	Symbol	rest Conditions	Min	Тур	Max	Ullits
Operating Voltage	V _{IN}		2.0		5.5	V
Minimum Start-up Voltage		T _A = +25°C			2.0	V
Start-up Voltage Temperature Coefficient		For Reference Only		-2		mV/°C
Quiescent Current		SHDN = VIN, No external FET		100	200	μΑ
Quiescent Current	lα	SHDN = GND		0.35	1	μΑ
BRT Full scale bias current	IBRT	S/P = VIN, VBRT = GND, ILS = 0A	7.5	10.5	13.5	μА
BRT Light sensor current	IBRT	S/P = VIN, VBRT = GND, ILS = 100μA		110		μΑ
S/P Logic Low Voltage	V _{S/P}				0.6	V
S/P Logic High Voltage	V _{S/P}		1.4			V
S/P Input DC Bias Current		S/P = VIN	-1	0.05	1	μΑ
S/P PWM frequency			10		1000	KHz
S/P Pulse Width			50			ns
BRT PWM Voltage	VBRT	VS/P = VIN (DCS/P = 100%)	270	300	330	mV
BRT PWM Voltage	VBRT	DCS/P = 50%, FPWM = 100KHZ		150		mV
Feedback Comparator Offset	VOS	VFB – VBRT, VBRT = 0mV		4		mV
SRC peak current	IPK	HYST mode; T _A = +25°C	180	240	300	mA
Efficiency	η	VOUT = 18V, I _{LOAD} = 20mA, V _{IN} = 5.0V		92		%
DRV Sink/Source Current			140	200		mA
Maximum Switch On-Time	t _{ON}		10	15	20	μS
Minimum Switch Off-Time	t _{OFF}		240	350	460	ns
OVP Threshold Voltage	V_{OVP}		1.10	1.22	1.34	V
OVP Input Bias Current	love	V _{OVP} = 1V	-50		50	nA





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THEORY OF OPERATION

Basic PFM operation

The LX1994 dual mode PFM modulator is implemented in two switching modes: the hysteretic and Continuous Switching Mode (CSM).

In *hysteretic switching mode*, the basic PFM modulator logic/timing block uses a Fixed Peak Current/ Fixed Off Time where the switch turns on and allows the inductor current to ramp to a finite peak level then shuts off for a fixed duration of time. The basic modulation cycle repeats as long as the converter output voltage is less than the maximum regulation level. When the maximum regulation level is reached, the switch remains off until the output voltage capacitor discharges to a level less than the minimum regulation level. The input signals to the switch logic block are the burst on/off control signal and the peak current detection signals. For low and negligible switch conduction losses, the peak current comparator at V_{HYST} corresponding to 200mA of output current is fixed.

In *Continuous Switching Mode* (CSM), the level to the peak current comparator is variable. This current level is developed by integrating the output of the feedback comparator which functions as a high gain bandwidth limited error amplifier. This current is clamped to the peak switch current limit of 600mA. The integrated capacitor is attached at the CMP pin when the burst on/off control line is forced to the "ON" state.

The conversion from hysteretic to CSM mode is performed when the burst length exceeds more than 16 switching cycles counting by an internal 16 bits shift register. The internal register is clocked by the switch transitions during each burst period. When the switching cycles exceed 16 cycles, the converter automatically switches over to CSM mode. CSM mode switching is latched by a J/K flip-flop. The conversion from CSM mode to hysteretic mode is performed when the error amplifier output falls below $V_{\rm CSM}$ (corresponding to 100mA peak current) as determined by a comparator. This resets the J/K flip-flop and converts back to hysteric mode.

In CSM mode, the switching frequency is varied depending on the input voltage, and the output voltage with a fixed off time of 350nS.

$$Fsw = \frac{1}{T_{OFF}} \times \frac{V_{IN}}{V_{OUT} + V_{DIODE}}$$

The LX1994 is a highly efficient PFM boost converter; its design is based on dual mode PFM for driving a series of white or color LEDs. The advantage of PFM switching is to minimize system efficiency losses in both heavy and light load operations. The LX1994 does not require an external oscillator due to PFM dual modes switching.

In light load operation, the converter minimizes switching losses by delivering more energy than necessary during switching burst period than the inactivity coast period.

In heavy load condition, the converter uses the Continuous Switching Current Mode (CSM) regulation scheme. This minimized peak switching current and thereby minimizes the conduction losses.

Losses

There are two types of losses in PFM regulator design: the switching loss, and conduction loss; that contribute to system inefficiency.

Switching loss: Energy switching losses are associated with a NFET's switch changing state (from on to off or vice versa) as a simultaneous high level of voltage and current are at the NFET's switch during the transition. This switching loss is proportional to the switching frequency.

Conduction loss: the loss due to current flow in the series resistance of the switch, inductor, and current sense resistor. Conduction loss is proportional to the square of the switch current.

Output Current Selection

The LED output current is regulated by adjusting of the FB pin voltage. If the FB pin voltage equals the BRT pin voltage, the LED current is the result of the FB pin voltage divided by the selected current sense resistor.

For example: in a 100% duty cycle design, FB pin voltage is 300mV, the current sense resistor is 15Ω . The LED current equals:

$$\frac{300\text{mV}}{15\Omega} = 20\text{mA}$$



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THEORY OF OPERATION (CONTINUED)

Dimming Modes

Microsemi's LX1994 provides two dimming options: PWM or DC voltage input.

PWM dimming

A PWM signal applied to S/P pin (see figure 4). This PWM signal is scaled to the reference such that a N% duty cycle PWM signal will produce an LED current of

$$\frac{\left\{N\% \bullet \left(10\,\mu A + I_{LS}\right) \bullet \left(R_{BRT} // 30k\Omega\right)\right\}}{R_{FB}}$$

Where $30k\Omega$ and $10\mu A$ are the internal values of the resistor and bias current respectively.

(See Fig. 1 for more details.)

If a light sensor (such as Microsemi's LX1970) is used, the light sensor current is applied to the LS pin and adds to the $10\mu A$ internal current source; in this case the internal current source determines the adjustment range in a pitch black ambient. The PWM signal will scale the light sensor signal allowing the dimming range to increase as the ambient light increases.

DC dimming mode

In "DC dimming mode" (see figure 5) the BRT pin input voltage can be applied directly to BRT pin with the S/P pin pulled high or developed indirectly by applying a PWM signal to the S/P pin and using a scaling resistor and filter capacitor at the BRT pin. The internal current source produces a $10\mu A$ reference current that is scaled by the resistance applied to the BRT pin.

Protection and IC Shutdown

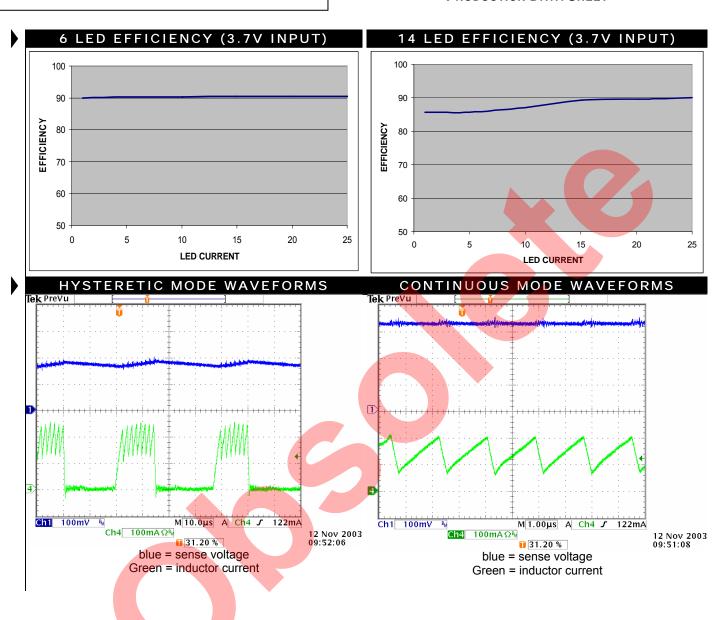
OVP: The LX1994 provides OVP protections. If the voltage at the OVP pin exceeds the internal reference voltage (1.2V), the converter will suspend switching. The converter will attempt to regulate the OVP pin to its nominal 1.2V.

IC Shutdown: To force the IC into shutdown mode, the S/P pin must pull low for a duration longer 100μs. In shutdown mode, the switch is off and the LED string current typically reduces to a few nano amps of leakage current.





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APPLICATION CIRCUITS

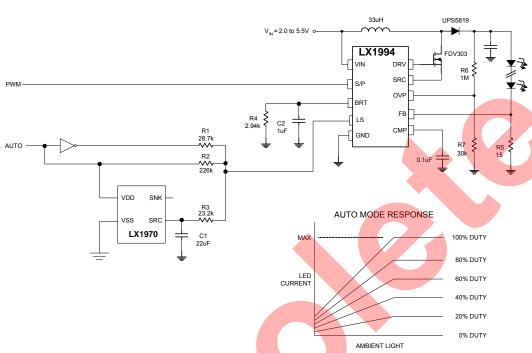


Figure 2 –PWM Dimming applied to S/P Input and Light Sensor (Dimming option 1)

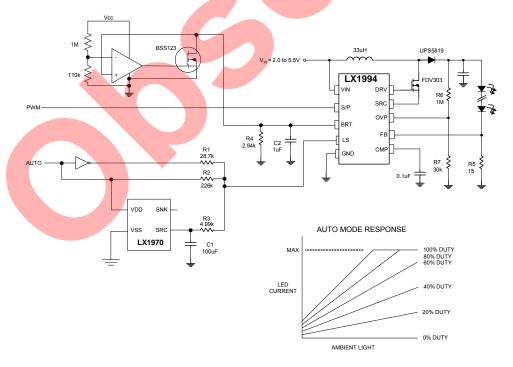


Figure 3 –PWM Dimming applied to S/P Input and Light Sensor (Dimming option 2)



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APPLICATION CIRCUITS

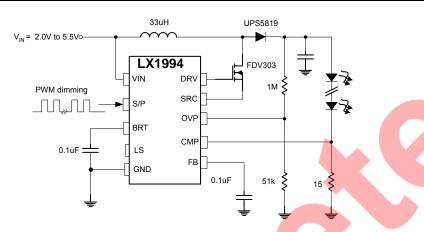


Figure 4 – LED Driver with PWM Dimming applied to S/P Input

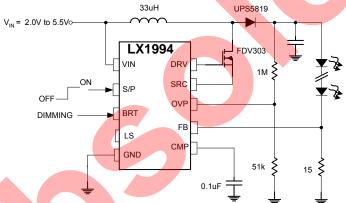


Figure 5 – LED Driver with DC Dimming applied to BRT Input

Note: The component values shown are only examples for a working system. Actual values will vary greatly depending on desired parameters, efficiency, and layout constraints.



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APPLICATION INFORMATION

OVP PROGRAMMING

Resistors R6 and R7 of Figure 2 program the over voltage clamp level. The value of R6 can be as high (like $1M\Omega$.) to minimize the quiescent current. The value of R7 can be determined using the following equation where VOVP is found in the ELECTRICAL CHARACTERISTICS TABLE:

$$R7 = R6 \times \left(\frac{V_{OVP}}{V_{OUT} - V_{OVP}} \right)$$

DESIGN EXAMPLE:

Let R6 equal 1M and the required clamp voltage is 25V.

$$R7 = 1M\left(\frac{1.2}{25 - 1.2}\right) = 50.4K\Omega$$

INDUCTOR AND CAPACITOR SELECTION

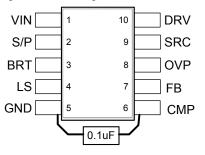
The output filter capacitor should be a $1\mu F$ capacitor with sufficient voltage rating for the OVP setting. Inductors in the range of $10\mu H$ to $47\mu H$ work best. For the best efficiency a larger value of inductor such as $47\mu H$ is recommended; larger value inductors will reduce ripple current which reduces peak currents and improves efficiency. Smaller value inductors may be use less board space, so a design trade off is in order.

TRANSISTOR AND DIODE SELECTION

A Schottky diode should be used with a 1 Amp current rating and voltage rating equivalent to the OVP setting. The transistor should be a N-channel MOSFET with a logic level gate voltage: good candidates are the FDV303N and the FDN337. For higher voltages, several BSS138 can be wired in parallel.

LAYOUT GUIDELINES

The LX1994 requires a tight layout of the CMP pin capacitance. For best results, the $0.1\mu F$ CMP capacitor should be located directly adjacent to the LX1994 package with etch lengths as short as possible.



LIGHT SENSOR INTERFACE

The LX1994 has a LS input pin to simplify the interface to an LX1970 light sensor. Two different circuits are described which provide slightly different response curves. The equations for calculating the component values are also given.

For the circuit of Figure 2, the describing equations are:

$$Rp = \frac{R4 \times 30k}{R4 + 30k}$$
 or $G4 = Gp - \frac{1}{30k}$

Auto Mode:

$$I_{LED} = \frac{DutyCycle}{R5} \times \begin{bmatrix} \frac{\left(I_{SRC} + 10\mu A\right) \times \left(R1 \times R2 \times Rp\right)}{\left(R1 \times R2\right) + \left(R1 \times Rp\right) + \left(R2 \times Rp\right)} \\ + \frac{V_{CC} \times \left(R1 \times Rp\right)}{\left(R1 \times R2\right) + \left(R1 \times Rp\right) + \left(R2 \times Rp\right)} \end{bmatrix}$$

$$I_{SRC(MAX)} = \frac{V_{CC} - V_{COMPLIANCE} - V_{BRT(MAX)}}{R3}$$

Manual Mode:

$$I_{LED} = \frac{DutyCycle}{R5} \times \begin{bmatrix} \frac{10\mu A \times (R1 \times R2 \times Rp)}{(R1 \times R2) + (R1 \times Rp) + (R2 \times Rp)} \\ + \frac{V_{CC} \times (R2 \times Rp)}{(R1 \times R2) + (R1 \times Rp) + (R2 \times Rp)} \end{bmatrix}$$

Example:

Select R5 = 15 ohms; ILED = 20mA max; ISRC clamp at $100\mu A$; VCC = 3.3; ILED in full darkness and 100% duty cycle = 4mA.

With R5 = 15 ohms; ILED = 20mA max, VBRT(MAX) = 300mV.

With ISRC clamp at $100\mu A$, Vcompliance (LX1970) = 0.68V, VCC = 3.3V, so

$$R3 = \frac{\left(3.3 - 0.68 - 0.3\right)}{100\mu\text{A}} = 23.2\text{k}$$



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APPLICATION INFORMATION

R3 = 23.2k

The level at 100% duty cycle in full darkness is 4mA, which is 20% of the maximum level of 20mA; this implies 80% is attributable to I_{SCR} . Combining this information with the describing equation for AUTO mode gives:

$$80\% \times I_{\text{LED(MAX)}} \times R5 = \frac{I_{\text{SRC}} \times (R1 \times R2 \times Rp)}{(R1 \times R2) + (R1 \times Rp) + (R2 \times Rp)}$$

This implies:

$$\frac{\left(R1 \times R2 \times Rp\right)}{\left(R1 \times R2\right) + \left(R1 \times Rp\right) + \left(R2 \times Rp\right)} = \frac{0.8 \times .02 \times 15}{100 \mu A} = 2.4k$$

Since the left side is the three resistors in parallel, this can be restated as:

$$416 \times 10^{-6} = \frac{1}{R1} + \frac{1}{R2} + \frac{1}{Rp} = G1 + G2 + Gp$$

The manual mode equation can be reduced to this assuming 100% duty and 20mA LED current (that is 0.3V sense resistor voltage):

$$\frac{R2 \times Rp}{R2 + Rp} = \frac{0.3 \times R1}{(10\mu A \times R1) + V_{CC} - 0.3} = \frac{0.3 \times R1}{(10\mu A \times R1) + 3.0}$$

This can be restated as:

$$\frac{1}{R2} + \frac{1}{Rp} = 33 \times 10^{-6} + \frac{10}{R1}$$
 or $G2 + Gp = 33 \times 10^{-6} + (10 \times G1)$

The auto mode equation can be reduced to this assuming 100% duty, 100µA ISRC current and 20mA LED current (that is 0.3V sense resistor voltage):

$$\frac{R1 \times Rp}{R1 + Rp} = \frac{0.3 \times R2}{\left((I_{SRC} + 10\mu A) \times R2\right) + V_{CC} - 0.3}$$

$$= \frac{0.3 \times R2}{\left((100\mu + 10\mu A) \times R2\right) + V_{CC} - 0.3} = \frac{0.3 \times R2}{\left(110\mu A \times R2\right) + 3.0}$$

This can be restated as:

$$\frac{1}{R1} + \frac{1}{Rp} = 367 \times 10^{-6} + \frac{10}{R2}$$
 or $G1 + Gp = 367 \times 10^{-6} + (10 \times G2)$

The equations above can be solved for G1, G2 and Gp:

$$G1=34.8\times10^{-6}$$

$$G2=4.45\times10^{-6}$$

$$Gp=376\times10^{-6}$$

Knowing Gp we can find

$$G4=Gp-\frac{1}{30k}=343\times10^{-6}$$

The resistance values are the reciprocal of the conductance's so:

$$R1 = 28.7k$$

$$R2 = 225k$$

$$R4 = 2.91k$$

The value of C1 is selected to give a time constant of $\frac{1}{2}$ second and works into R3 (which is 23.2k).

$$C1 = \frac{0.5}{23.2k}$$
 $C1 = 21.5 \mu F$

The value of C2 works into Rp and the pole should be set at 1/100 of the PWM frequency.

$$C2 = \frac{1}{6.28 \times \frac{10 \text{kHz}}{100} \times 2.66 \text{k}}$$

For a 10KHz PWM, C2 = 599nF, and a value of $1\mu f$ works well.

Circuit of Figure 3:

The second light sensor interface is very similar to the first; the choice is a matter of user preference. In the second circuit, an active 325mV clamp is used to clamp the maximum LED current in auto mode.

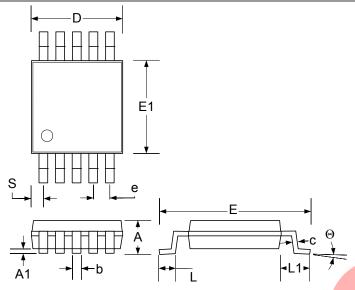
In this circuit, resistor R3 is reduced to extend the operating ambient light range of the light sensor and filter capacitor C1 must therefore be increased.



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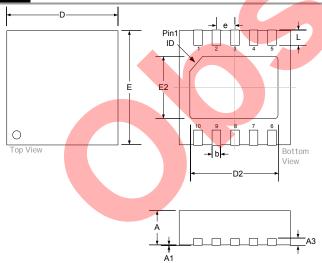
PACKAGE DIMENSIONS

DU 10-Pin Miniature Shrink Outline Package (MSOP)



	MILLIMETERS		INCHES		
Dim	MIN	MAX	MIN	MAX	
Α	_	1.10	-	0.043	
A1	0.05	0.15	0.002	0.006	
b	0.15	0.30	0.006	0.012	
С	0.13	0.23	0.005	0.009	
D	2.90	3.10	0.114	0.122	
е	0.50 BSC		0.020 BSC		
Е	4.75	5.05	0.187	0.198	
E1	2.90	3.10	0.114	0.122	
L	0.41	0.70	0.016	0.028	
L1	0.95 BSC		0.037 BSC		
S	0.50 BSC		0.020		
Θ	0°	6°	0°	6°	

LD 10-Pin Plastic Micro Lead frame Package (MLP)

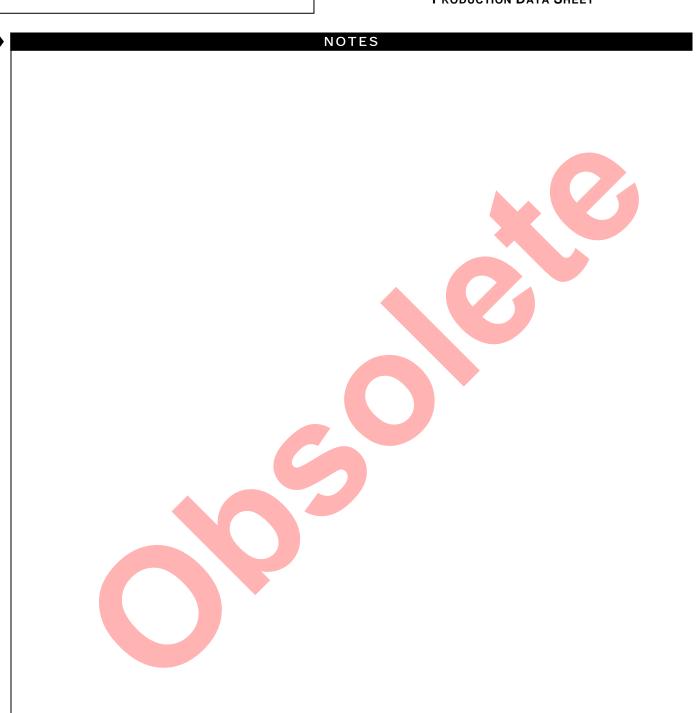


	MILLIMETERS		INCHES		
Dim	MIN	MAX	MIN	MAX	
Α	0.80	1.00	0.0315	0.0394	
A1	0	0.05	0	0.0019	
A3	0.20 REF		0.0079 REF		
b	0.18	0.30	0.0071	0.0118	
D	3.00 BSC		0.1181 BSC		
D2	2.23	2.48	0.0878	0.0976	
е	0.50 BSC		0.019	7 BSC	
Е	3.00 BSC		0.1181 BSC		
E2	1.49	1.74	0.0587	0.0685	
L	0.30	0.50	0.0071	0.0197	

Note: Dimensions do not include mold flash or protrusions; these shall not exceed 0.155mm(.006") on any side.



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